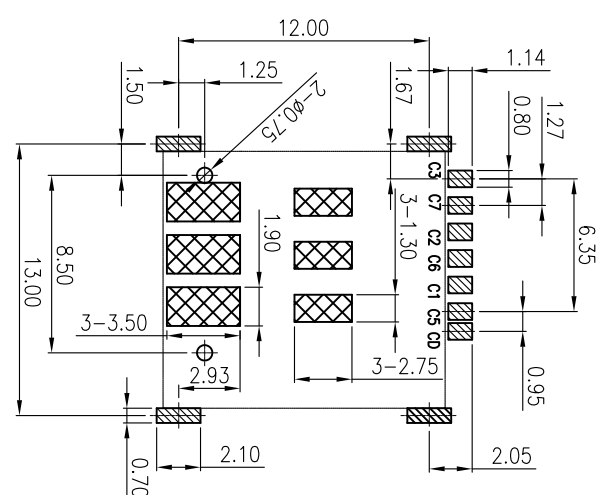
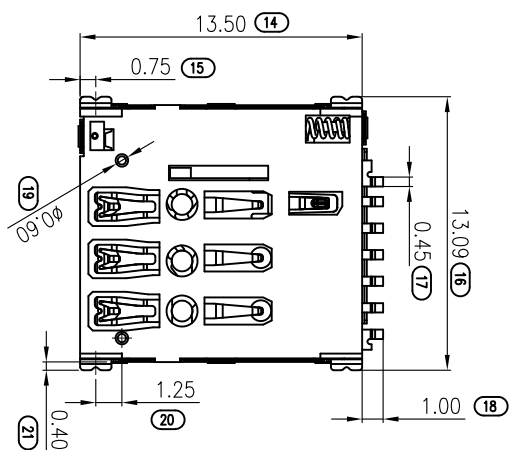
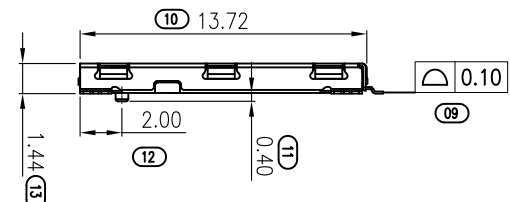
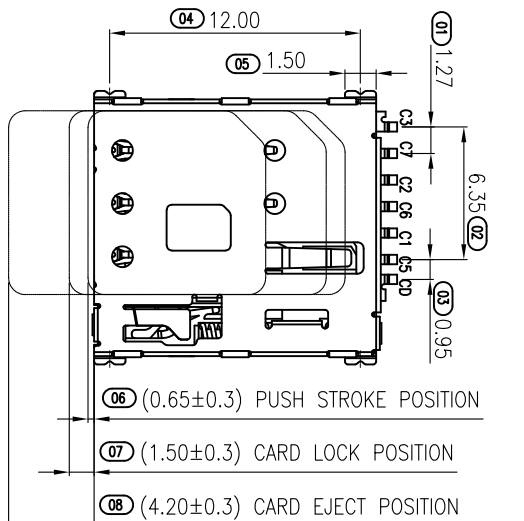
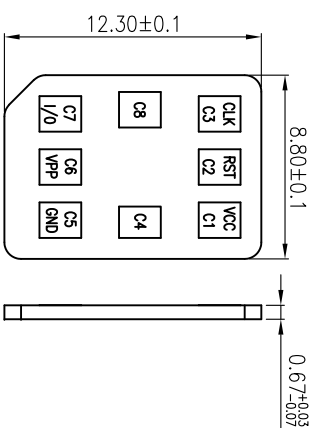
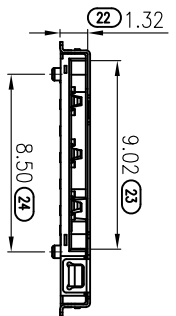


ROHS

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		新版发行	2021.09.17	MO	TEDDY	SUNNILEY



RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05



- NOTES:
- 1) MATERIAL:  
HOUSING:HI-TEMP. PLASTIC UL 94V-0  
CONTACT:COOPER ALLOY  
SHELL:STAINLESS STEEL
  - 2) PLATING :  
TERMINAL:  
CONTACT AREA: AU GOLD FLASH;  
SOLDER AREA: AU GOLD FLASH;  
UNDER PLATE: NICKEL;  
SHELL: NICKEL PLATED OVER ALL.  
SOLDER AREA: GOLD FLASH.
  3. SPECIALTY:  
3.1 Rated current:1.0A  
3.2 Rated voltage:30V  
3.3 Contact Resistance:50mΩ MAX  
3.4 Insulation Resistance:1000MΩ MIN 500V DC  
3.5 Dielectric withstanding voltage: 500V AC.  
3.6 Solder ability:260+0/-5°C, 50±10s.  
3.7 Durability:5000 Cycles Min.  
3.8 Operating condition:Temperature:-40°C~+85°C;  
Humidity 80% RH MAX

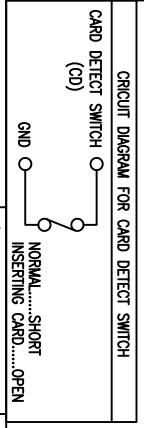


**MINTRON TECHNOLOGY CO.,LTD.**

PART NUMBER: MT102314442  
TITLE: (NS005-010) NANO SIM CARD PUSH PUSH 7PIN 1.37H 非CD PIN 非CD PIN 非CD PIN 非CD PIN (非CD PIN)

APPR: C-102314442-00  
CHKD: DWG NO.:  
DRE: SCALE: 1:1  
SHEET: 1/2  
REV: A0

SIM pin Assignment	PIN#	Name	MILLIMETERS	INCH	UNITS	MM
	C1	VCC	X ± 0.30	X ± 0.012	MAT'L	SEE NOTES
	C2	RST	XX ± 0.20	XXX ± 0.008	FINISH	SEE NOTES
	C3	CLK	.XXX ± 0.10	.XXXX ± 0.004	QTY	SEE NOTES
	C4	GND				
	C5	VPP				
	C6	VPP				
	C7	I/O				



A B C D E

A B C D E

1 2 3 4 5

1 2 3 4 5